

8.0A FAST RECOVERY RECTIFIER BRIDGE
RECTIFIER Reverse Voltage – 600 to 1000 V
Forward Current – 8.0A

FEATURES

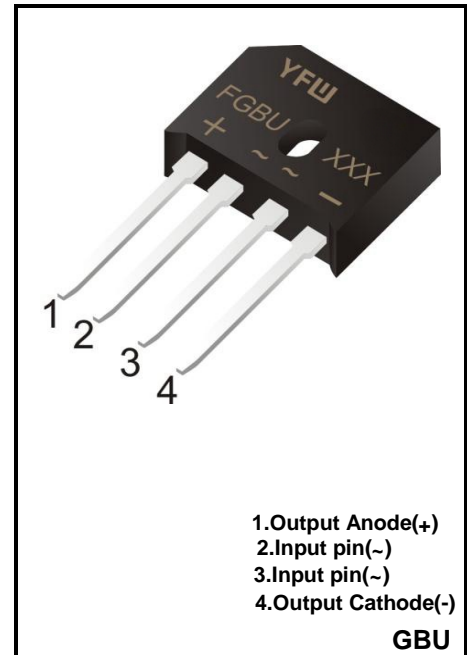
- ◆Ultrason soft recovery
- ◆LOW I_{RRM} , LOW V_F , LOW V_{RRM}
- ◆Glass Passivated Chip Junction
- ◆Special frame design for heat dissipation
- ◆Lead free in comply with EU RoHS 2011/65/EU directives

BENEFITS

- ◆Reduced EMI
- ◆Reduced Power loss and switching transistor
- ◆Reduced snubbing

MECHANICAL DATA

- ◆Case: GBU
- ◆Terminals: Solderable per MIL-STD-750, Method 2026
- ◆Approx. Weight: 3.9g /0.138oz



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

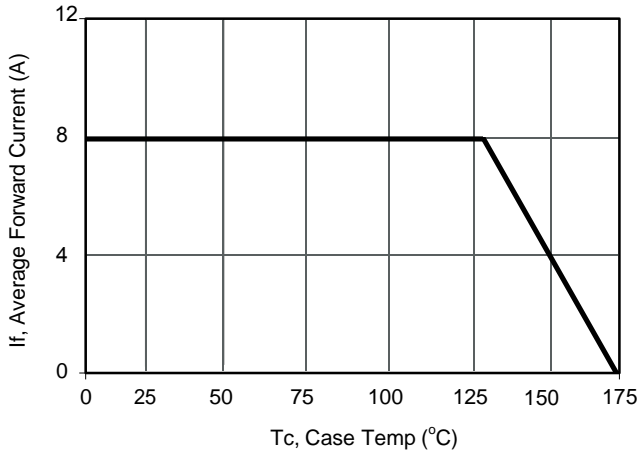
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FGBU806	FGBU808	FGBU810	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	600	800	1000	V
Maximum RMS voltage	V_{RMS}	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	600	800	1000	V
Average Rectified Output Current	I_o	8.0			A
Reverse Recovery Time. $I_F=0.5A, I_R=1A, I_{RR}=0.25A$	T_{rr}	500			nS
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load(JEDEC method)	I_{FSM}	175			A
I^2t Rating for Fusing(1ms≤t≤10ms)	I^2t	127			A ² S
Maximum Forward Voltage at 4.0 A	V_F	1.25			V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	5 100			uA
Typical Junction Capacitance (Note1)	C_j	50			pF
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +175			°C

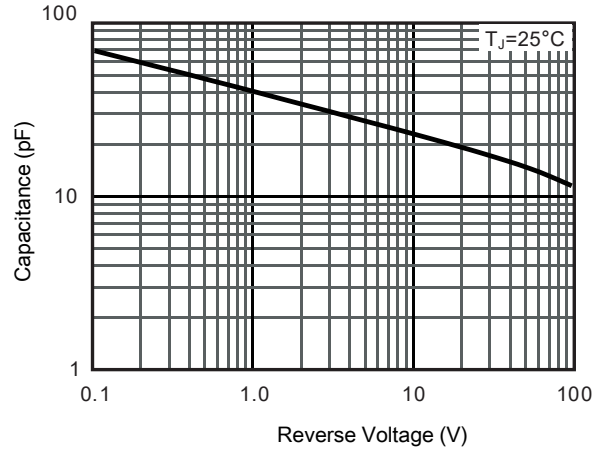
Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

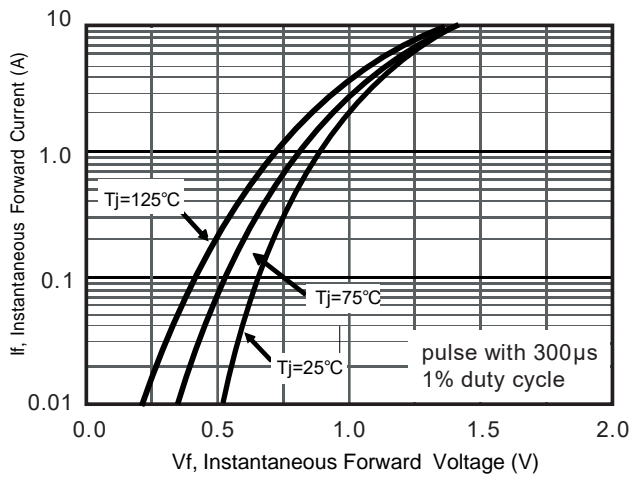
RATINGS AND CHARACTERISTICS CURVES (TA = 25 °C unless otherwise noted)



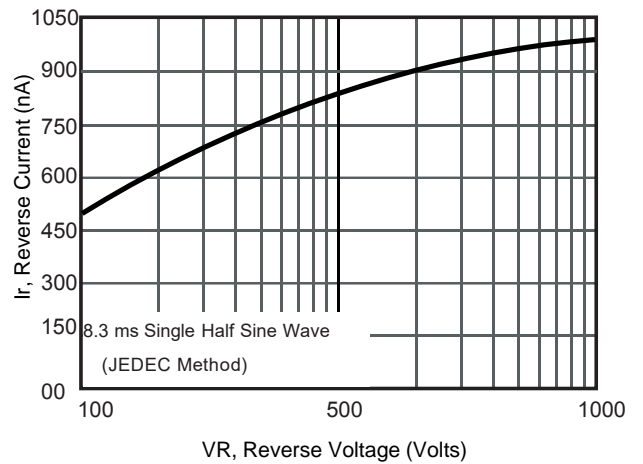
Current Derating, Case



Typical Junction Capacitance

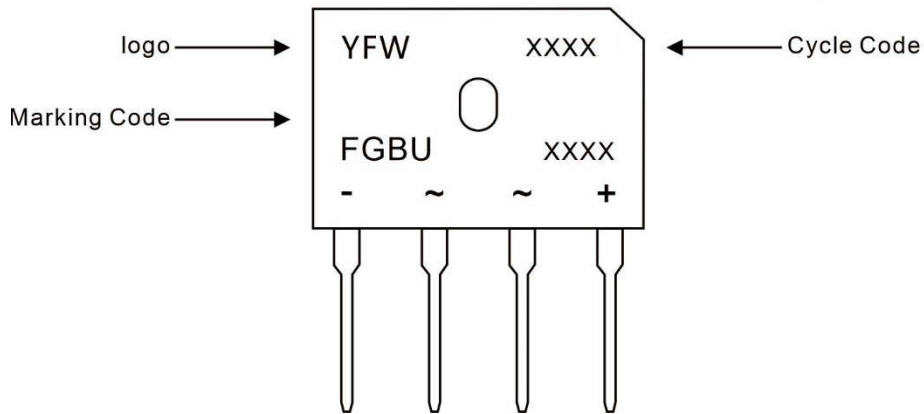


Typical Forward Voltage



Typical Reverse Current

Marking Diagram



Ordering information

Package	Packing Description	Packing Quantity
GBU	bulk	500PCS/Box 5000PCS/Carton

Package Dimensions

GBU

The drawing shows the package dimensions in millimeters and inches. The dimensions are defined as follows:

- A:** Overall width
- B:** Overall height
- C:** Diameter of the central hole
- D:** Distance from the top edge to the center of the hole
- E:** Height of the package body
- F:** Height of the first pin
- G:** Height of the second pin
- H:** Distance between the first and last pins
- I:** Pitch between pins
- J:** Length of the package body
- K:** Length of the first pin
- L:** Total length including pins
- M:** Length of the second pin

Dim	Millimeter(mm)		Dimensions inInch	
	Min.	Max.	Min.	Max.
A	21.70	22.30	0.86	0.88
B	18.20	18.80	0.72	0.74
C	3.70	3.90	0.146	0.154
D	1.60	2.00	0.06	0.08
E	1.80	2.20	0.07	0.09
F	2.00	2.40	0.08	0.09
G	0.90	1.30	0.04	0.05
H	3.00	/	0.12	/
I	4.88	5.28	0.19	0.21
J	3.20	3.60	0.13	0.14
K	1.70	2.10	0.07	0.08
L	17.50	18.50	0.69	0.73
M	0.40	0.60	0.02	0.02

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